

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	6	semiconductor and (((heat with treat\$4) or anneal\$3 or heat\$3) with lamp) and (lamp with ((beam with linear) and puls\$3))	US-PGPUB; USPAT	ADJ	ON	2009/02/26 11:18
L5	0	4 and @ad<"20001010"	US-PGPUB; USPAT	ADJ	ON	2009/02/26 11:19
L6	6303	(438/166,308,378,486-487,509,522,530,795).OCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2009/02/26 11:36
L7	0	((heating with radiation with lamp) and (first inactive gas) and (second inactive gas) and cooling and (opposite with surface)).clm.	US-PGPUB; USPAT	ADJ	ON	2009/02/26 12:32
S18	3	09/970908	US-PGPUB; USPAT	OR	OFF	2009/02/25 18:08
S19	279	semiconductor and (((heat with treat\$4) or anneal\$3 or heat\$3) with lamp) and (light with puls\$3 with linear)	US-PGPUB; USPAT	ADJ	ON	2009/02/25 18:24
S20	29	S19 and @ad<"20001010"	US-PGPUB; USPAT	ADJ	ON	2009/02/25 18:30
S21	157	semiconductor and (((heat with treat\$4) or anneal\$3 or heat\$3) with lamp) and (halogen with lamp) and (cylindrical with len with optical)	US-PGPUB; USPAT	ADJ	ON	2009/02/25 18:46
S22	20	S21 and @ad<"20001010"	US-PGPUB; USPAT	ADJ	ON	2009/02/25 18:46
S23	136	semiconductor and (((heat with treat\$4) or anneal\$3 or heat\$3) with lamp) and (halogen with lamp) and (cylindrical with len with optical) and puls\$3	US-PGPUB; USPAT	ADJ	ON	2009/02/25 18:48
S24	14	S23 and @ad<"20001010"	US-PGPUB; USPAT	ADJ	ON	2009/02/25 18:48

S25	463	semiconductor and (((heat with treat\$4) or anneal\$3 or heat\$3) with lamp) and (halogen with lamp) and (beam with linear) and puls\$3	US-PGPUB; USPAT	ADJ	ON	2009/02/25 19:04
S26	3	semiconductor and (((heat with treat\$4) or anneal\$3 or heat\$3) with lamp) and ((halogen with lamp) with (beam with linear)) and puls\$3	US-PGPUB; USPAT	ADJ	ON	2009/02/25 19:04
S27	61	S25 and @ad<"20001010"	US-PGPUB; USPAT	ADJ	ON	2009/02/25 19:05

**2/ 26/ 2009 12:34:17 PM**

**C:\ Documents and Settings\ bau\ My Documents\ EAST\ Workspaces\ Heating and Cooling Processes\ 10625737 heating by lamp with coolant flow and rapid cooling after heat up of substrate.wsp**